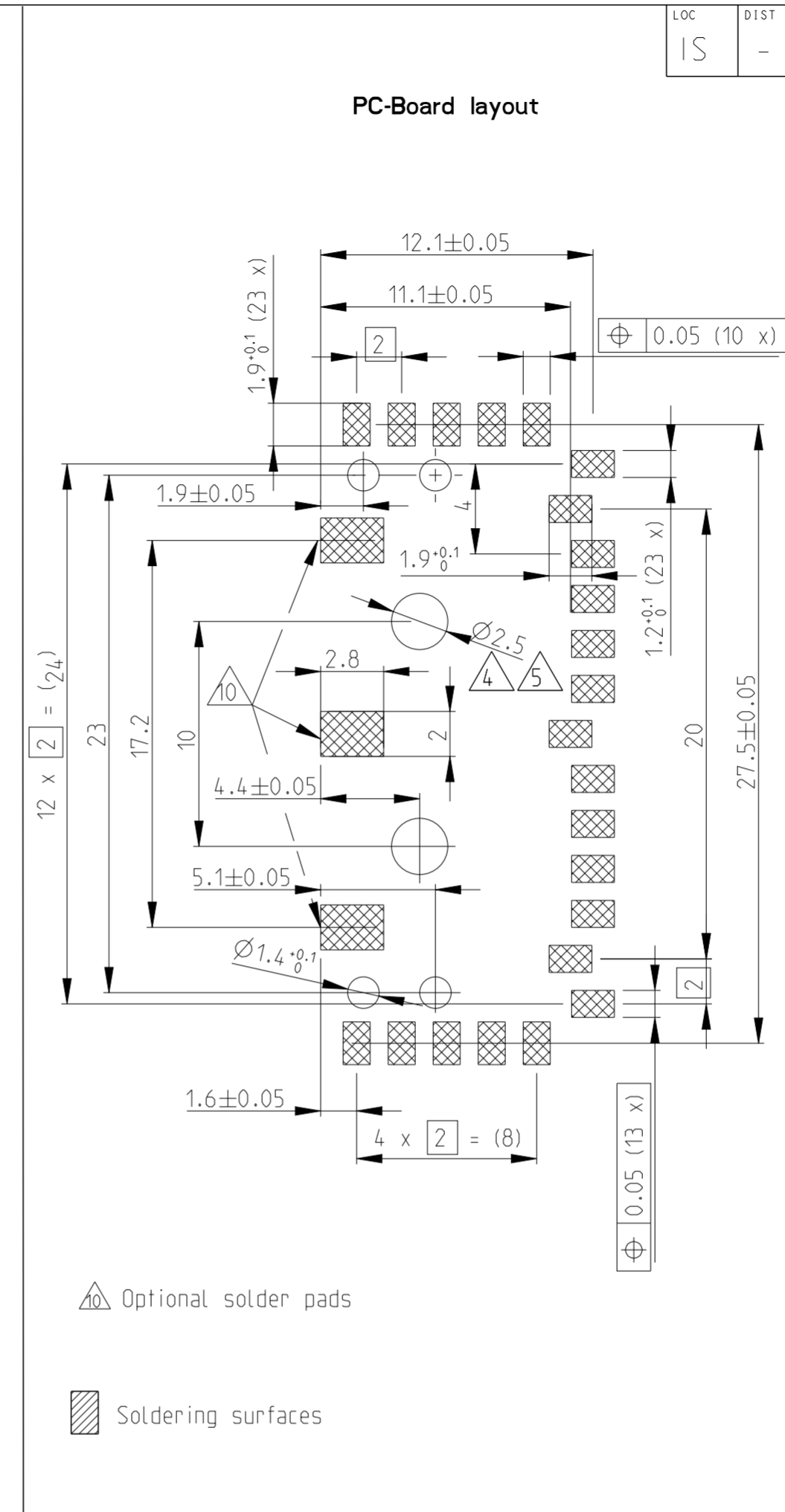
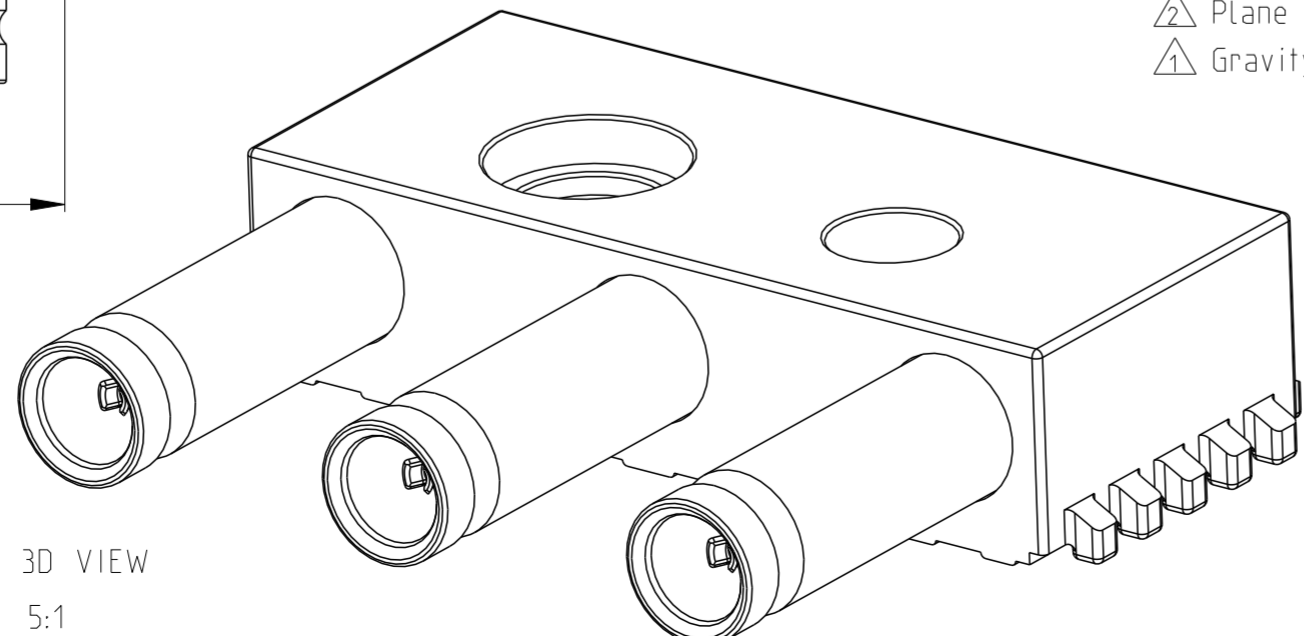
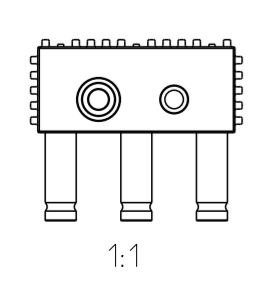
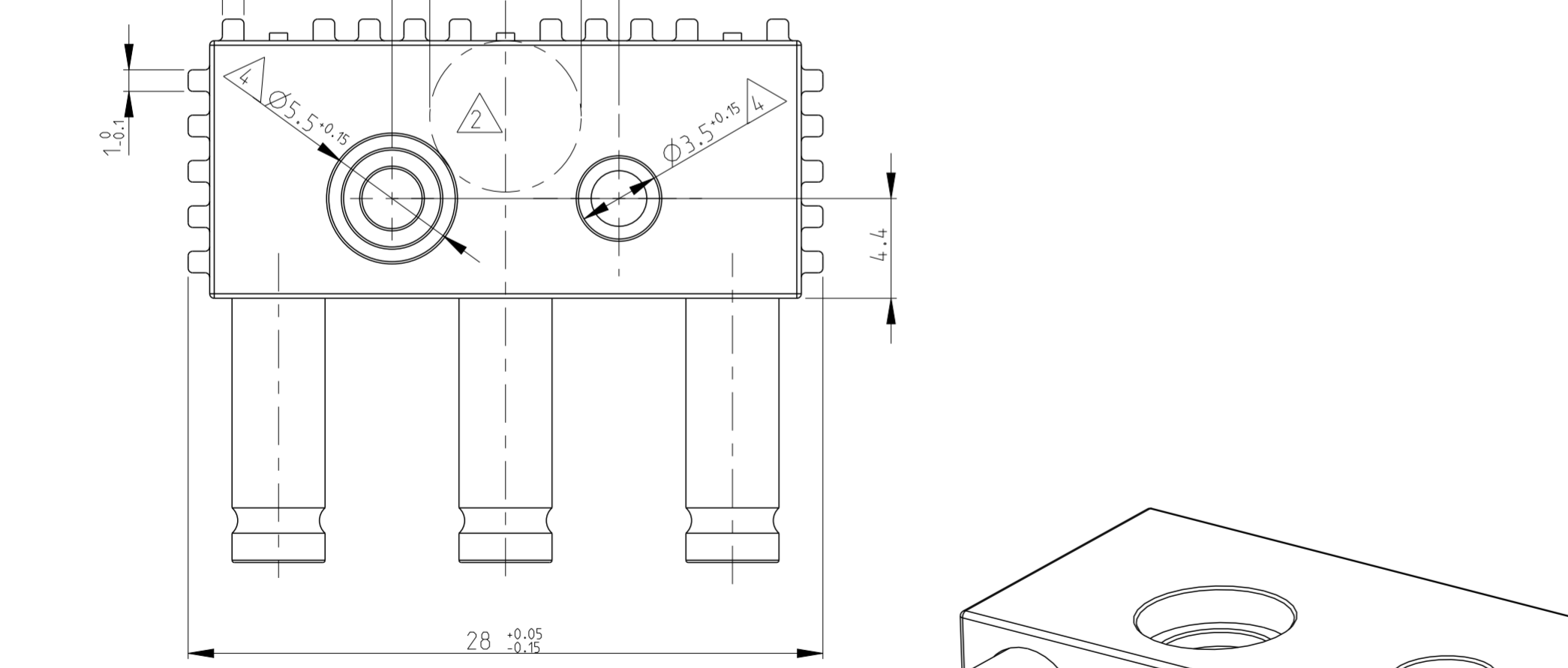
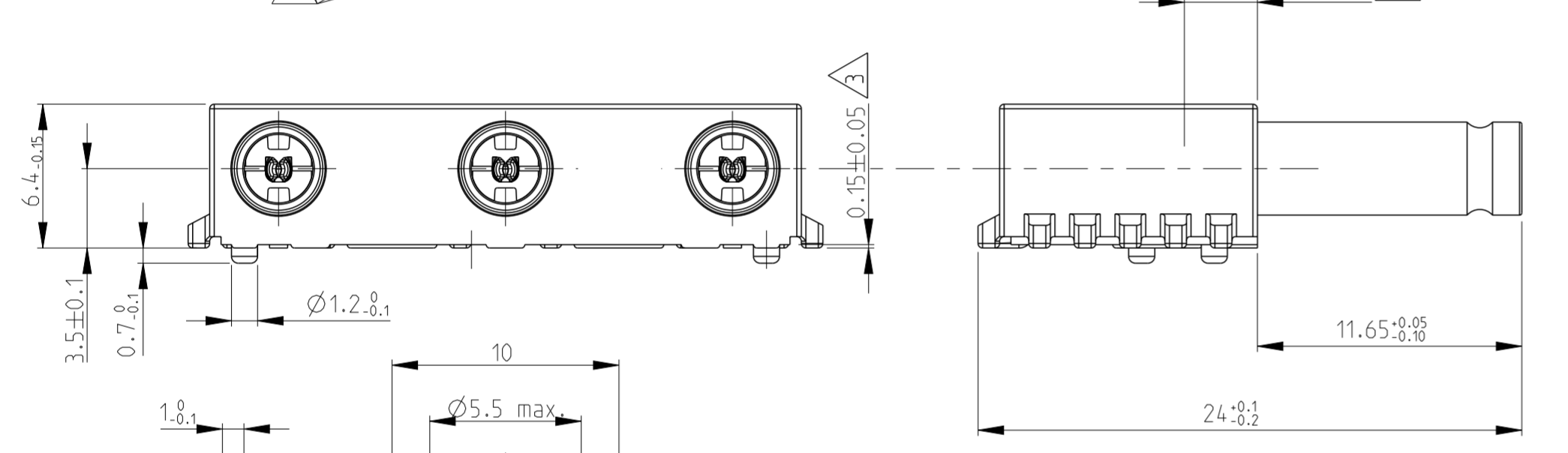
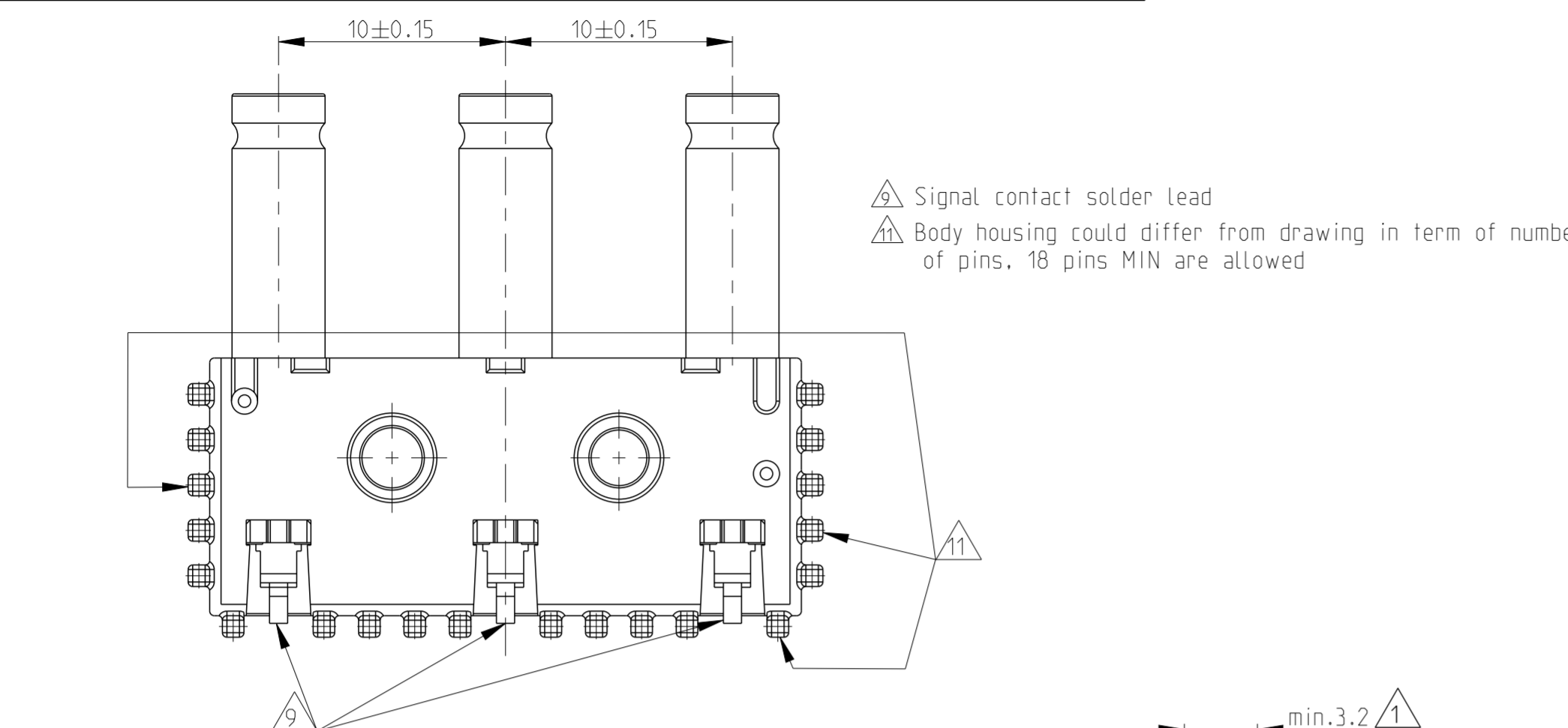


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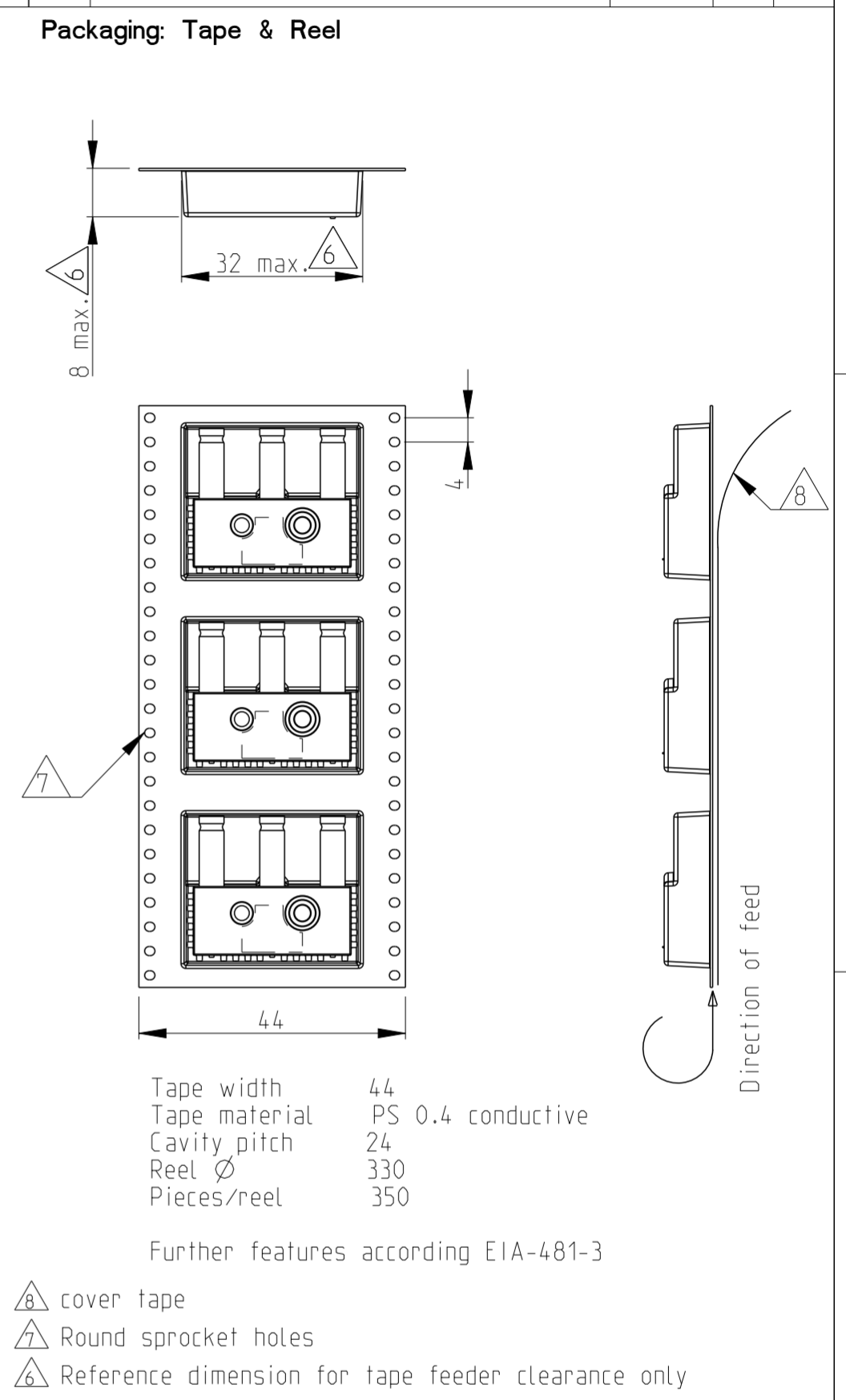
REVISIONS				
P	LTR	DESCRIPTION	DATE	APVD
A2		Update drawing - note 11 added	20FEB2012	MS MG



- Optional solder pads
- Soldering surfaces

Coplanarity of all SMD solder terminals: 0.15 max.
 Component weight: 10 gram max.

- Diameter depending on placement tolerances
- Hole suitable for screw M2.5
- Stand off
- Plane surface for automatic placement
- Gravity point



TE nr	Description	Material	Plating
619401-1	Dielectric	PCT	-
	Center conductor	Bronze	Contact area: min. 1 µm Au (Gold) over min. 1µm Ni (Nickel) Solder area: min. 3 µm Sn (Tin)
	Outer conductor	Brass	Min. 0.1 µm Au (Gold) over min. 2µm NiP (Nickel-Phosphorum) over min 0.2 Cu (Copper) (all the plating thickness are measured in contact area)
	Body	ZnAl4	Min. 2 µm Sn (Tin)

THIS DRAWING IS A CONTROLLED DOCUMENT. DWN A.Mariotti 03APR2009
 CHK D.Bozzer 03APR2009

DIMENSIONS: mm	TOLERANCES UNLESS OTHERWISE SPECIFIED:	APVD -	NAME 1.0-2.3 Jack 3 posn Siemax SMD solder
0 PLC ±±	1 PLC ±±±	PRODUCT SPEC 108-90019	SIZE CAGE CODE DRAWING NO RESTRICTED TO
2 PLC ±±±±	3 PLC ±±±±±	APPLICATION SPEC -	A2100779 C-619401
4 PLC ±±±±±±	ANGLES ±	WEIGHT -	SCALE 4:1 SHEET 1 OF 1 REV A2
MATERIAL -	FINISH -	CUSTOMER DRAWING	

STE TE Connectivity